

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Cancelled)

2. (Currently Amended) A film carrier tape for mounting an electronic part, comprising an elongated insulating film having a plurality of wiring patterns formed on a surface of the insulating film, said wiring patterns being made of a conductive metal and at least two of said wiring patterns being arranged side by side in the width direction of the elongated insulating film, wherein:

the wiring patterns are each independently covered with a solder resist layer except a connecting terminal portion, and the solder resist layer formed on each surface of the wiring patterns is divided into plural sections;

wherein an area occupied by one film carrier is substantially the same as an area of an electronic part to be mounted on the film carrier tape; and

wherein in each film carrier, a distance between one section and its adjacent section of the divided solder resist layer is in the range of 20 μ m to 3 mm.

3-9. (Canceled)

10. (Previously Presented) The film carrier tape for mounting an electronic part as claimed in claim 2, wherein the solder resist layer is formed on each surface of the wiring patterns in such a manner that the solder resist layer is divided into 2 to 16 sections.

11. (Cancelled)

12. (Previously Presented) The film carrier tape for mounting an electronic part as claimed in claim 2, wherein the elongated insulating film has a thickness of not more than 75 μm .

13. (Cancelled)

14. (Previously Presented) The film carrier tape for mounting an electronic part as claimed in claim 2, wherein an opposite surface to the surface of the insulating film where the wiring pattern of the film carrier for mounting an electronic part is formed is designed so that metal balls to be electrically connected outside the film carrier can be arranged.

15. (Previously Presented) The film carrier tape for mounting an electronic part as claimed in claim 2, wherein the solder resist layer formed on the surface of the wiring pattern has an average thickness, except non-solder resist area, of 3 to 50 μm after curing.

16. (Previously Presented) The film carrier tape for mounting an electronic part as claimed in claim 2, wherein the solder resist layer is formed in a region of not less than 20% of the wiring patterns except the connecting terminal portions.